860

Silicone Heat Transfer Compound

860 is a thermal paste designed to reduce thermal resistance between irregular metal surfaces. Coupled with reasonable thermal conductivity, it has a soft consistency and a wide operating temperature range, making it an ideal thermal paste for CPU applications.

This silicone-based thermal paste is mostly used to improve heat flow between heat sinks and heat-generating components, such as CPUs, GPUs, LEDs, motors, and power components.

Features & Benefits

- High dielectric strength
- Excellent corrosion resistance
- Non-bleeding heat transfer paste
- Non-electrically conductive
- Long service life

Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
860-4G	Pouch	1.7 mL	4 g
860-60G	Jar	25 mL	60 g
860-150G	Tube	62.5 mL	150 g
860-1P	Jar	470 mL	1.13 kg
860-3.78L	Pail	3.78 L	9.07 kg

Storage and Handling

Store between 0 and 30 °C in a dry area, away from sunlight (see SDS).

Properties

Color	White	
Filler	Zinc oxide	
Base Material	Silicone oil	
Density	2.4	g/mL
Viscosity	490	Pa·s
Resistivity	1.5×10^{15}	Ω·cm
Thermal Conductivity @ 25 ˚C	0.7	W/(m·K)
Evaporation Loss, 22 h @ 165 ˚C	0.1	%
Oil Separation, 30 h @ 165 ˚C	0.7	%
Worked Penetration, ½ scale	303	
Water Washout @ 38 ˚C, Bearing Dried @ 77 ˚C	0.1	%
Dielectric Strength	400	V/mil
Dielectric Constant	3.8	
Dissipation Factor	0.003	
Service Temperature Range	-40–200	˚C

Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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